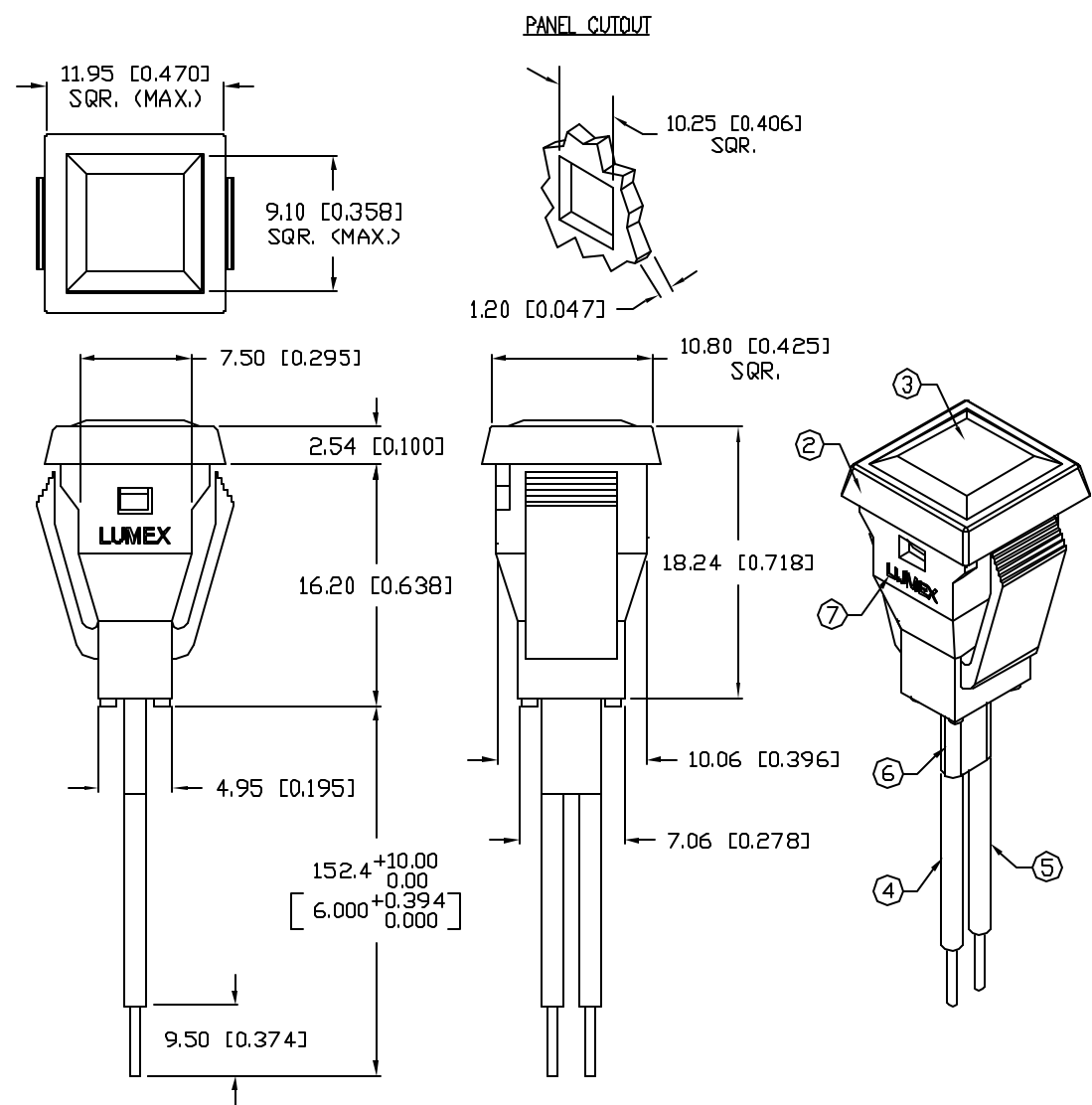


UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SSI-LXMP5011SRC150		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10808. & REDRAWN IN 3D.	11.2.01



ELECTRO-OPTICAL CHARACTERISTICS T_A=25°C I_f=20mA

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.8	2.2	V _f	
REVERSE VOLTAGE	4.0			V _r	I _f =100μA
AXIAL INTENSITY		60		med	I _f =20mA
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C

* t < 10μs

- NOTES:
- SSL-LX4D73SRD LED, RED. (INSIDE)
 - SSH-LXMP5011 HOLDER, BLACK.
 - LXP-LXN5011C, WATER CLEAR LENS.
 - ANODE LEAD: LXP-WST24RDT0C, 24 AWG STRANDED, TOP OVERCOAT, RED INSULATION, CUT 180mm LONG, STRIP 4mm & 9.5mm.
 - CATHODE LEAD: LXP-WST24BLT0C, 24 AWG STRANDED, TOP OVERCOAT, BLACK INSULATION, CUT 180mm LONG, STRIP 4mm & 9.5mm.
 - HEAT SHRINK: LXP-HEATSHRINK-4, 1/8" x 1/2". (1 PIECE)
 - 'LUMEX' ON FRONT (ANODE SIDE) OF PART.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+0.00}/_{-0.00} MAX= ^{+0.00}/_{-0.00}

REV.	PART NUMBER
A	SSI-LXMP5011SRC150

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12mm SQUARE PANEL INDICATOR WITH LENS,
 660nm RED LED, WATER CLEAR LENS, 6" WIRE LEADS.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
BC			7.1.99
			PAGE: 1 OF 1
			SCALE: N/A